1.8 nV/√Hz, 36 V Precision Amplifiers
ADA4004-1/ADA4004-2/ADA4004-4

FEATURES

Very low voltage noise: 1.8 nV/√Hz
Low input bias current: 90 nA maximum
Offset voltage: 125 µV maximum
High gain: 120 dB
Wide bandwidth: 12 MHz
±5 V to ±15 V operation

APPLICATIONS

Precision instrumentation
Filter blocks
Microphone preamplifiers
Industrial control
Thermocouples and RTDs
Reference buffers

GENERAL DESCRIPTION

The ADA4004-1/ADA4004-2/ADA4004-4 are 1.8 nV/√Hz precision amplifiers featuring 40 µV offset, 0.7 µV/°C drift, 12 MHz bandwidth, and low 1.7 mA per amplifier supply current.

The ADA4004-1/ADA4004-2/ADA4004-4 are designed on the high performance *i*Polar™ process, enabling improvements such as reduced noise and power consumption, increased speed and stability, and smaller footprint size. Novel design techniques enable the ADA4004-1/ADA4004-2/ADA4004-4 to achieve 1.8 nV/√Hz voltage noise density and a low 6 Hz 1/f noise corner frequency while consuming just 1.7 mA per amplifier. The small package saves board space, reduces cost, and improves layout flexibility.

Applications for these amplifiers include high precision controls, PLL filters, high performance precision filters, medical and analytical instrumentation, precision power supply controls, ATE, and data acquisition systems. Operation is fully specified from ±5 V to ±15 V from −40°C to +125°C.

The ADA4004-1, ADA4004-2, and ADA4004-4 are members of a growing series of low noise op amps offered by Analog Devices, Inc. (see Table 1).

Table 1. Voltage Noise

Pkg.	0.9 nV	1.1 nV	1.8 nV	2.8 nV	3.8 nV
Single	AD797	AD8597	ADA4004-1	AD8675	AD8671
Dual		AD8599	ADA4004-2	AD8676	AD8672
Quad			ADA4004-4		AD8674

PIN CONFIGURATIONS
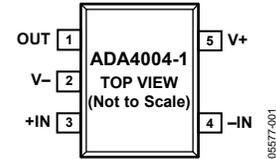
Figure 1. 5-Lead SOT
(RJ-5)
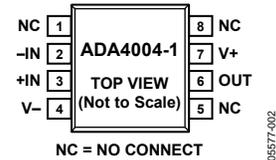
NC = NO CONNECT

Figure 2. 8-Lead SOIC
(R-8)
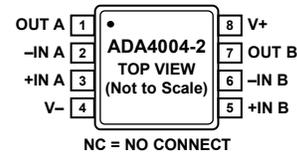
NC = NO CONNECT

Figure 3. 8-Lead MSOP (RM-8) and 8-Lead SOIC (R-8)
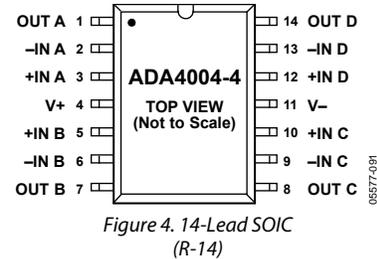

Figure 4. 14-Lead SOIC
(R-14)
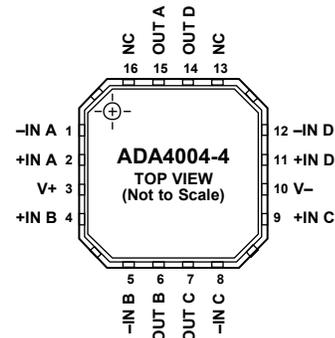
NOTES
1. NC = NO CONNECT.
2. IT IS RECOMMENDED THAT THE EXPOSED PAD
**   BE CONNECTED TO V−.**

Figure 5. 16-Lead LFCSP
(CP-16-4)

TABLE OF CONTENTS

REVISION HISTORY

SPECIFICATIONS

V_{SY} = ±5 V, V_{CM} = 0 V, T_A = 25°C, unless otherwise specified.

Table 2.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Offset Voltage	V_{OS}			40	140	µV
		−40°C ≤ T_A ≤ +125°C			300	µV
Input Bias Current	I_B			40	85	nA
		−40°C ≤ T_A ≤ +125°C			165	nA
Input Offset Current	I_{OS}			40	85	nA
		−40°C ≤ T_A ≤ +125°C			100	nA
Input Voltage Range	IVR		−3.5		+3.5	V
Common-Mode Rejection Ratio	CMRR	V_{CM} = −3.0 V to +3.0 V	105	111		dB
		−40°C ≤ T_A ≤ +125°C	95	110		dB
Open-Loop Gain	A_{VO}	R_L = 2 kΩ, V_{OUT} = −2.5 V to +2.5 V	250	400		V/mV
		−40°C ≤ T_A ≤ +125°C	170			V/mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	−40°C ≤ T_A ≤ +125°C		0.7	1	µV/°C
OUTPUT CHARACTERISTICS						
Output Voltage High	V_{OH}	R_L = 2 kΩ to ground	3.7	3.9		V
		−40°C ≤ T_A ≤ +125°C	3.4	3.6		V
Output Voltage Low	V_{OL}	R_L = 2 kΩ to ground		−3.6	−3.55	V
		−40°C ≤ T_A ≤ +125°C		−3.6	−3.4	V
Short-Circuit Limit	I_{SC}			25		mA
		−40°C ≤ T_A ≤ +125°C				mA
Output Current	I_O	V_{OUT} = ±3.6 V		±10		mA
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	V_{SY} = ±5 V to ±15 V	110	118		dB
		−40°C ≤ T_A ≤ +125°C	110			dB
Supply Current per Amplifier	I_{SY}				2.0	mA
		−40°C ≤ T_A ≤ +125°C			2.2	mA
DYNAMIC PERFORMANCE						
Slew Rate	SR	R_L = 2 kΩ to ground		2.7		V/µs
Gain Bandwidth Product	GBP			12		MHz
Phase Margin	Φ_M			48		Degrees
NOISE PERFORMANCE						
Voltage Noise	$e_{n\,p\text{-}p}$	f = 0.1 Hz to 10 Hz		0.1		µV p-p
Voltage Noise Density	e_n	f = 1 kHz		1.8		nV/√Hz
Current Noise Density	i_n	f = 10 Hz		3.5		pA/√Hz
Current Noise Density	i_n	f = 200 Hz		1.2		pA/√Hz

ADA4004-1/ADA4004-2/ADA4004-4

$V_{SY} = \pm 15$ V, $V_{CM} = 0$ V, $T_A = 25°C$, unless otherwise specified.

Table 3.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Offset Voltage	V_{OS}			40	125	µV
		$-40°C \le T_A \le +125°C$			270	µV
Input Bias Current	I_B			40	90	nA
		$-40°C \le T_A \le +125°C$			165	nA
Input Offset Current	I_{OS}				60	nA
		$-40°C \le T_A \le +125°C$			100	nA
Input Voltage Range	IVR		−12.5		+12.5	V
Common-Mode Rejection Ratio	CMRR	$V_{CM} = -12.5$ V to $+12.5$ V	110	113		dB
		$-40°C \le T_A \le +125°C$	100	104		dB
Open-Loop Gain	A_{VO}	$R_L = 2$ kΩ, $V_{OUT} = -12.0$ V to $+12.0$ V	500	1200		V/mV
		$-40°C \le T_A \le +125°C$	250	500		V/mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	$-40°C \le T_A \le +125°C$		0.7	1	µV/°C
OUTPUT CHARACTERISTICS						
Output Voltage High	V_{OH}	$R_L = 2$ kΩ to ground	13.4	13.6		V
		$-40°C \le T_A \le +125°C$	13.1	13.3		V
Output Voltage Low	V_{OL}	$R_L = 2$ kΩ to ground		−13.3	−13.2	V
		$-40°C \le T_A \le +125°C$		−13.25	−13.15	V
Short-Circuit Limit	I_{SC}			25		mA
Output Current	I_O	$V_{OUT} = \pm 13.6$ V		±10		mA
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	$V_{SY} = \pm 5$ V to ± 15 V	110	118		dB
		$-40°C \le T_A \le +125°C$	110			dB
Supply Current per Amplifier	I_{SY}				2.2	mA
		$-40°C \le T_A \le +125°C$			2.4	mA
DYNAMIC PERFORMANCE						
Slew Rate	SR	$R_L = 2$ kΩ to ground		2.7		V/µs
Gain Bandwidth Product	GBP			12		MHz
Phase Margin	Φ_M			48		Degrees
NOISE PERFORMANCE						
Voltage Noise	$e_{n\ p-p}$	$f = 0.1$ Hz to 10 Hz		0.15		µV p-p
Voltage Noise Density	e_n	$f = 1$ kHz		1.8		nV/√Hz
Current Noise Density	i_n	$f = 10$ Hz		3.5		pA/√Hz
Current Noise Density	i_n	$f = 200$ Hz		1.2		pA/√Hz

ABSOLUTE MAXIMUM RATINGS

Table 4.

Parameter	Rating
Supply Voltage	±18 V or +36 V
Input Voltage	V− < V_{IN} < V+
Differential Input Voltage	±V supply
Differential Input Current	±5 mA
Output Short-Circuit Duration to GND	Indefinite
Storage Temperature Range	−65°C to +150°C
Operating Temperature Range	−40°C to +125°C
Junction Temperature Range	−65°C to +150°C
Lead Temperature (Soldering 60 sec)	300°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL RESISTANCE

θ_{JA} is specified with the device soldered on a circuit board with its exposed paddle soldered to a pad (if applicable) on a 4-layer JEDEC standard printed circuit board with zero airflow.

Table 5.

Package Type	θ_{JA}	θ_{JC}	Unit
5-Lead SOT (RJ-5)	230	92	°C/W
8-Lead SOIC (R-8), ADA4004-1	177	53	°C/W
8-Lead SOIC (R-8), ADA4004-2	155	45	°C/W
8-Lead MSOP (RM-8)	186	52	°C/W
14-Lead SOIC_N (R-14)	115	36	°C/W
16-Lead LFCSP_VQ (CP-16-4)	44	31.5	°C/W

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

TYPICAL PERFORMANCE CHARACTERISTICS
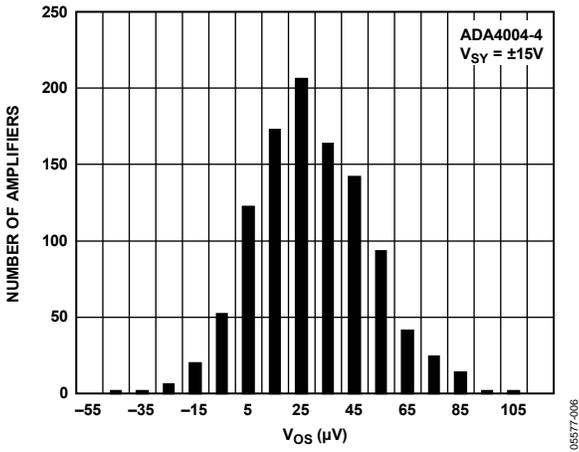
Figure 6. Number of Amplifiers vs. Input Offset Voltage
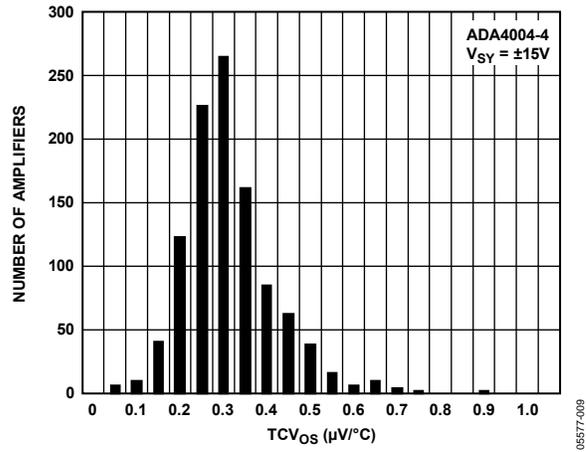

Figure 9. Number of Amplifiers vs. TCV_OS
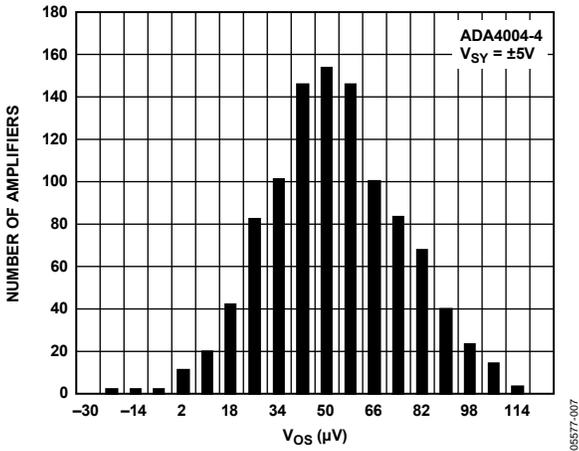
Figure 7. Number of Amplifiers vs. Input Offset Voltage
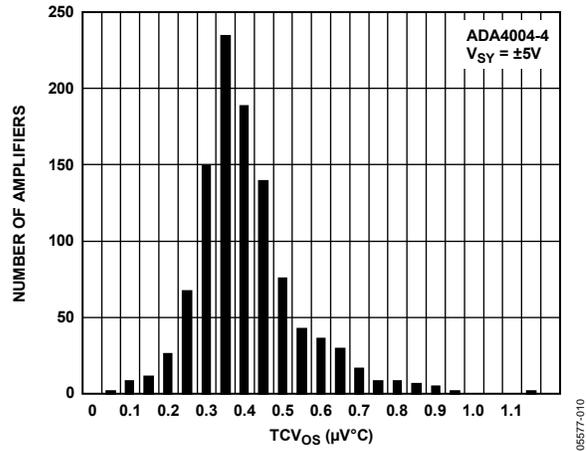
Figure 10. Number of Amplifiers vs. TCV_OS
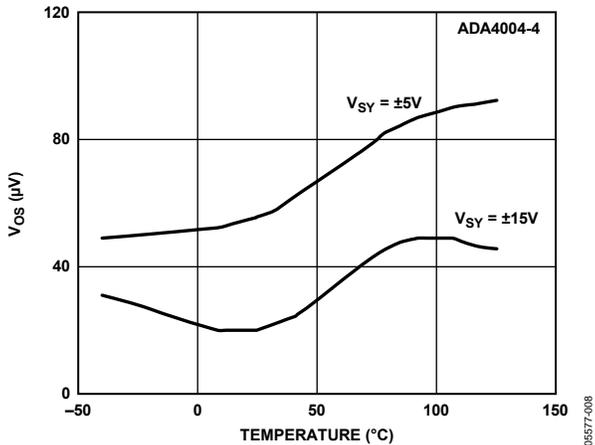

Figure 8. Input Offset Voltage vs. Temperature
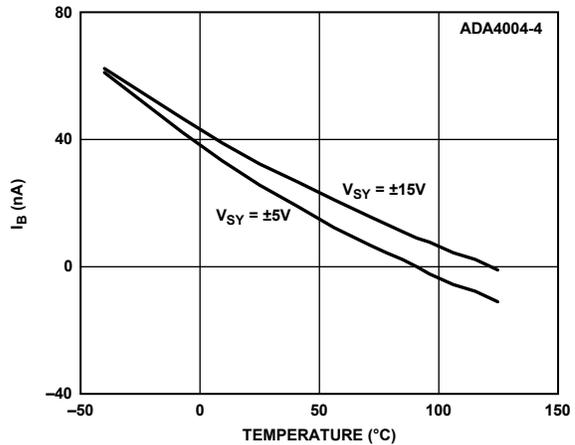
Figure 11. Input Bias Current vs. Temperature
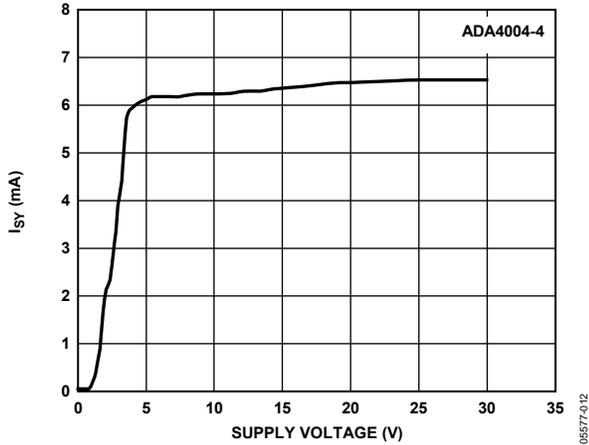
Figure 12. Supply Current vs. Total Supply Voltage
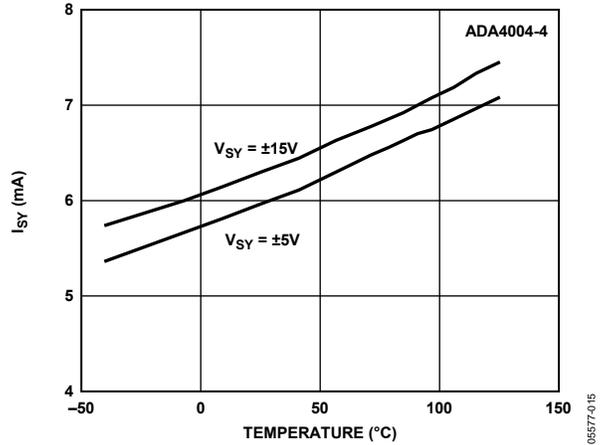
Figure 15. Supply Current vs. Temperature
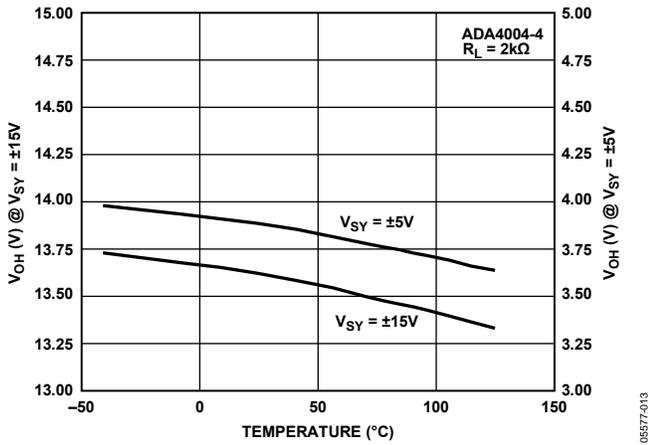
Figure 13. V_{OH} vs. Temperature
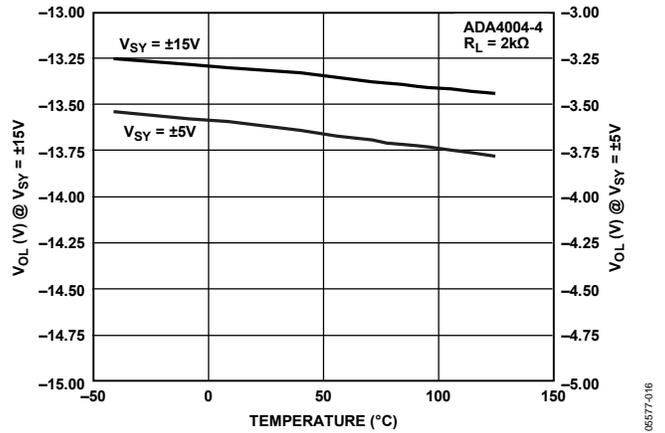

Figure 16. V_{OL} vs. Temperature
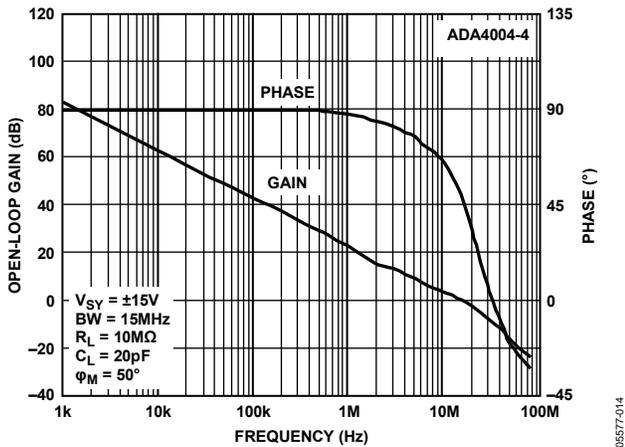
Figure 14. Open-Loop Gain and Phase vs. Frequency
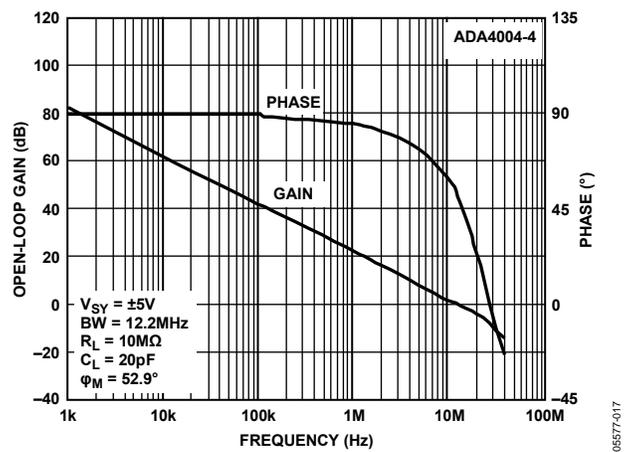

Figure 17. Open-Loop Gain and Phase vs. Frequency
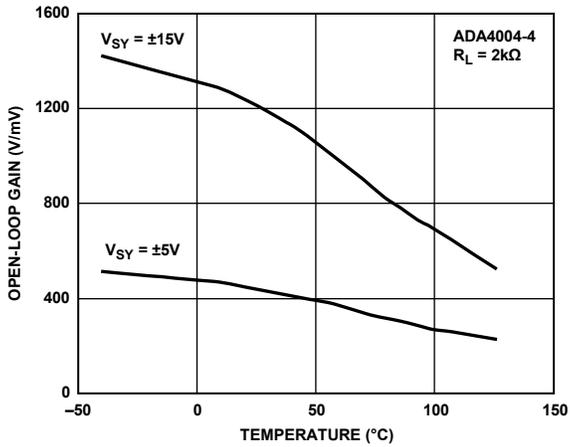
Figure 18. Open-Loop Gain vs. Temperature

Figure 19. Closed-Loop Gain vs. Frequency

Figure 20. Output Impedance vs. Frequency
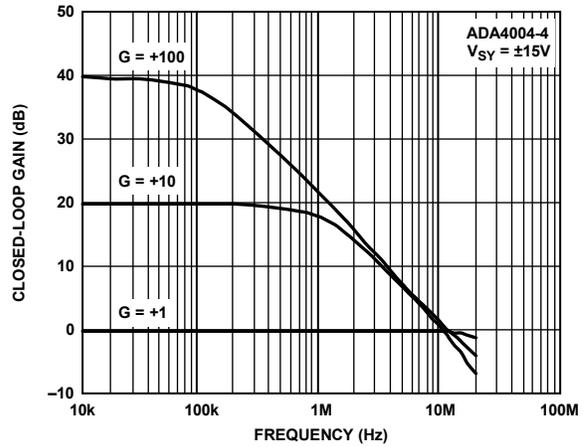
Figure 21. Closed-Loop Gain vs. Frequency
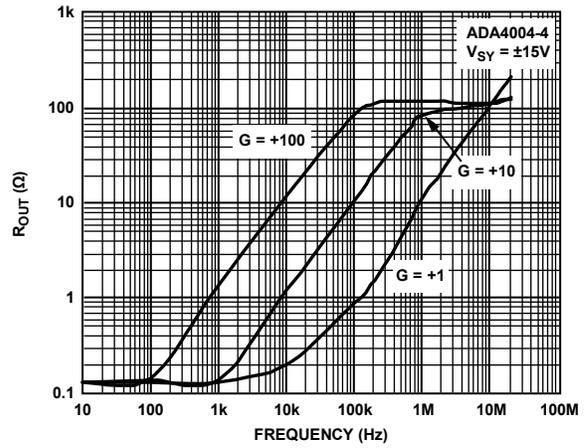
Figure 22. Output Impedance vs. Frequency
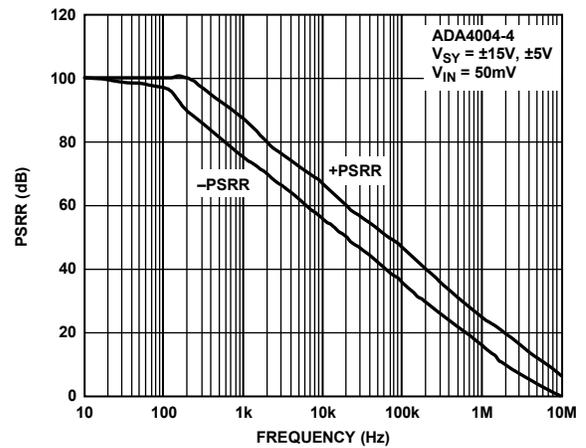
Figure 23. PSRR vs. Frequency
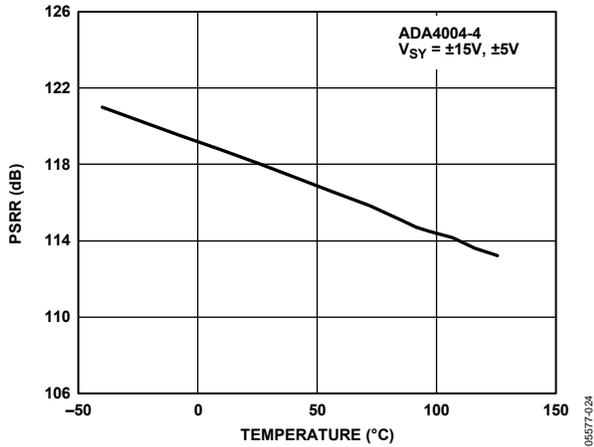
Figure 24. PSRR vs. Temperature
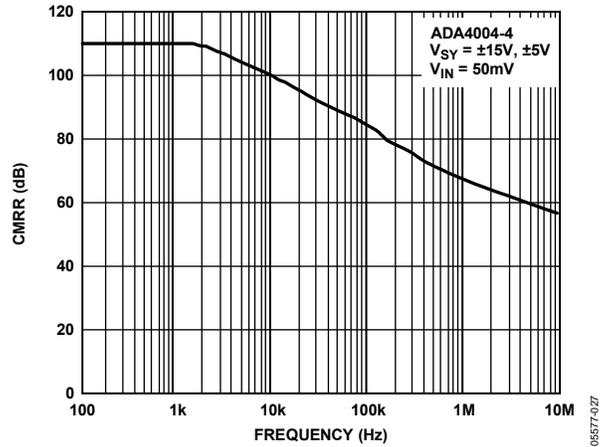

Figure 27. CMRR vs. Frequency
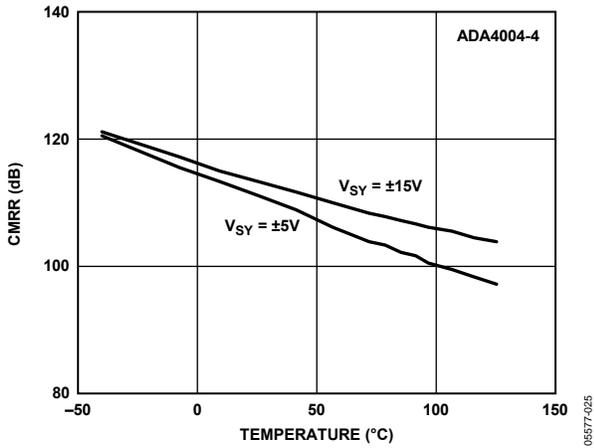
Figure 25. CMRR vs. Temperature
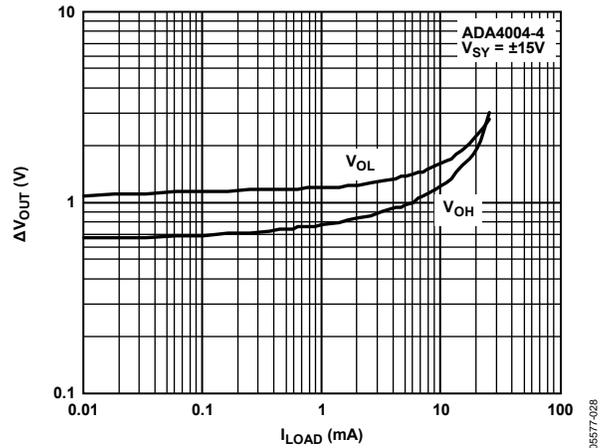
Figure 28. Output Voltage vs. Current Load
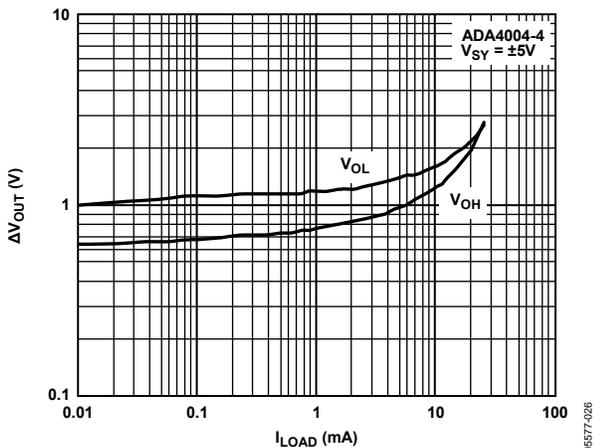
Figure 26. Output Voltage vs. Current Load
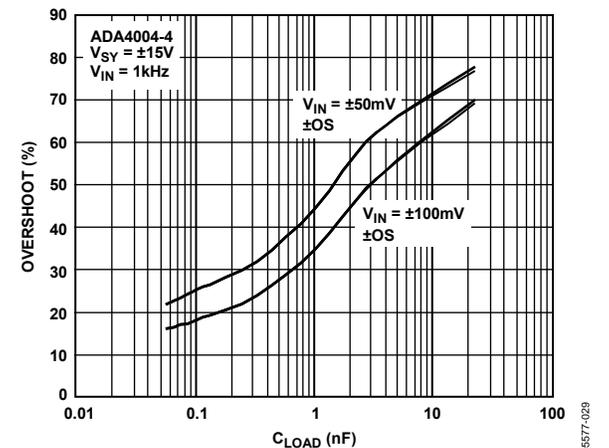
Figure 29. Small-Signal Overshoot vs. Capacitive Load
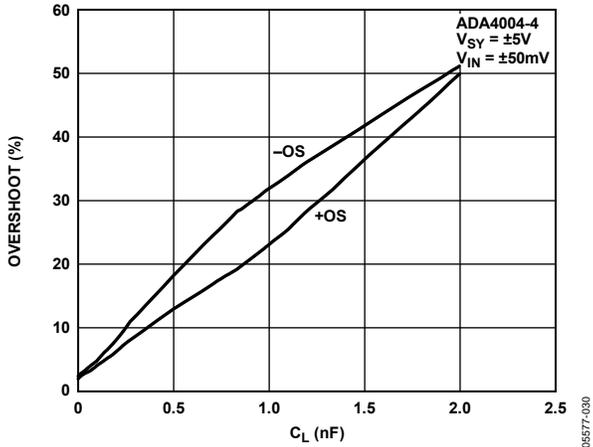
Figure 30. Small-Signal Overshoot vs. Capacitive Load
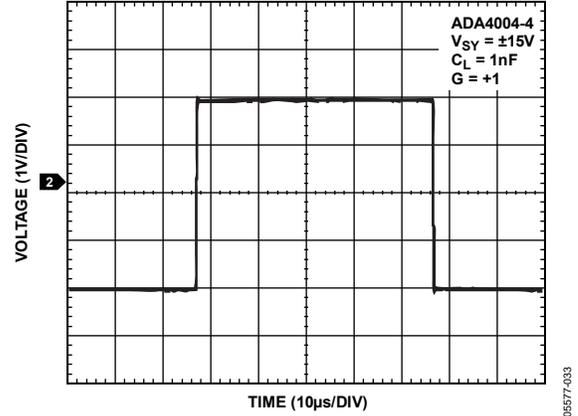
Figure 33. Large-Signal Transient Response
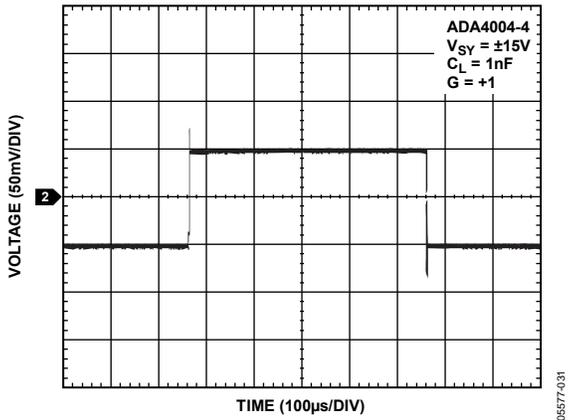
Figure 31. Small-Signal Transient Response
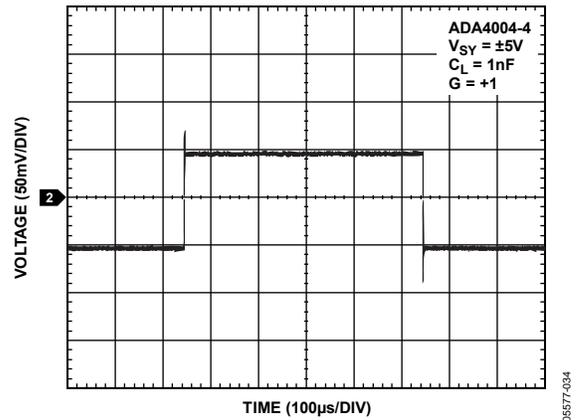
Figure 34. Small-Signal Transient Response
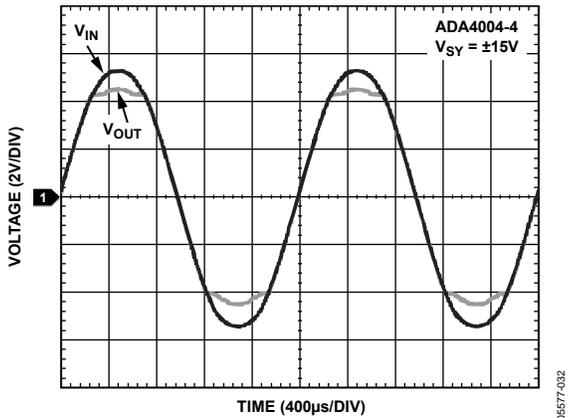
Figure 32. No Phase Reversal
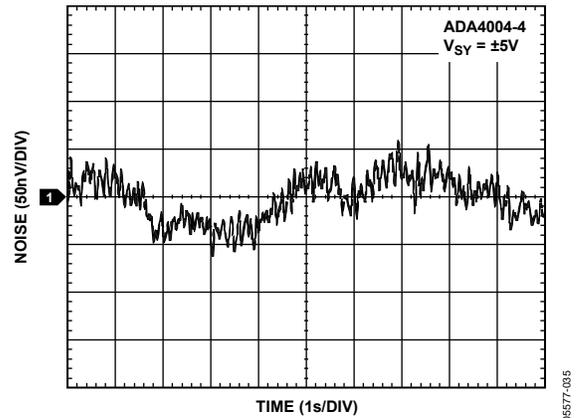
Figure 35. Voltage Noise (0.1 Hz to 10 Hz)
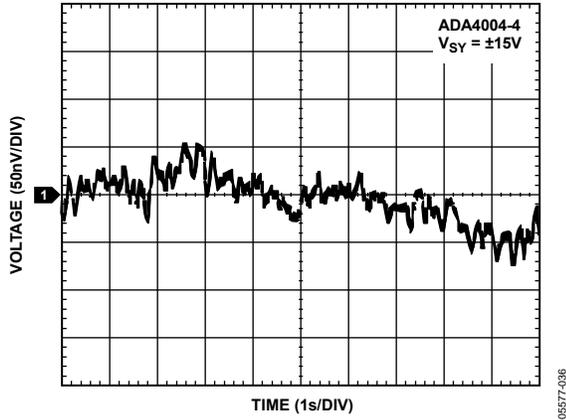
Figure 36. Voltage Noise (0.1 Hz to 10 Hz)
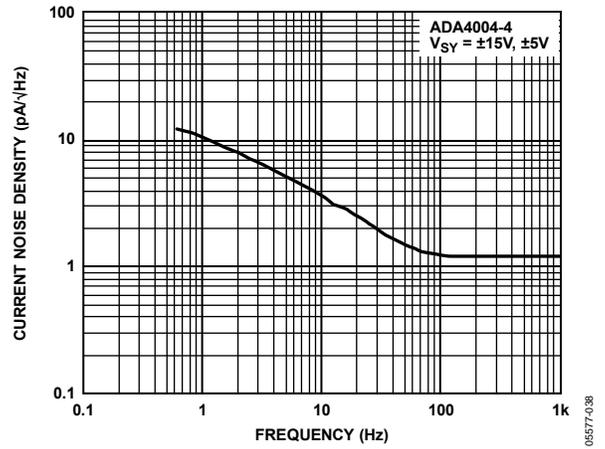
Figure 38. Current Noise Density vs. Frequency
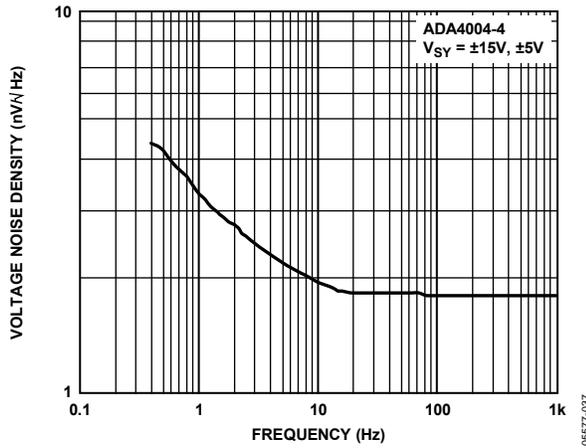
Figure 37. Voltage Noise Density vs. Frequency
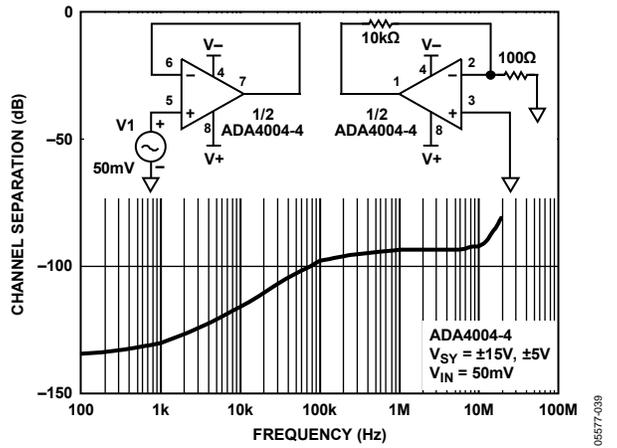
Figure 39. Channel Separation vs. Frequency

OUTLINE DIMENSIONS
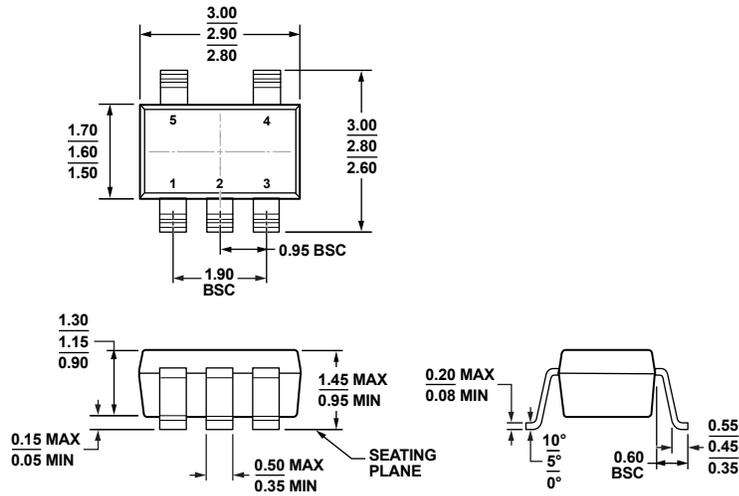
COMPLIANT TO JEDEC STANDARDS MO-178-AA

Figure 40. 5-Lead Small Outline Transistor Package [SOT-23]
(RJ-5)
Dimensions shown in millimeters
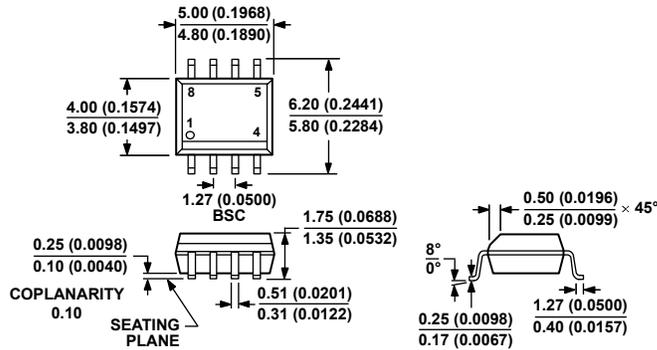
COMPLIANT TO JEDEC STANDARDS MS-012-AA
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 41. 8-Lead Standard Small Outline Package [SOIC_N]
Narrow Body (R-8)
Dimensions shown in millimeters and (inches)

3.20
3.00
2.80

8   5

3.20
3.00
2.80

5.15
4.90
4.65

1   4

PIN 1
IDENTIFIER

0.65 BSC

0.95
0.85
0.75

1.10 MAX

15° MAX

0.15
0.05
COPLANARITY
0.10

0.40
0.25

6°
0°

0.23
0.09

0.80
0.55
0.40

10-07-2009-B

COMPLIANT TO JEDEC STANDARDS MO-187-AA

Figure 42. 8-Lead Mini Small Outline Package [MSOP]
(RM-8)
Dimensions shown in millimeters

4.00
BSC SQ

PIN 1
INDICATOR

TOP
VIEW

3.75
BSC SQ

0.60 MAX

0.60 MAX

(BOTTOM VIEW)

PIN 1
INDICATOR

13   16   1

0.65 BSC

12

EXPOSED
PAD

2.25
2.10 SQ
1.95

0.75
0.60
0.50

9   4

8   5

0.25 MIN

1.95 BSC

12° MAX

0.80 MAX
0.65 TYP

0.05 MAX
0.02 NOM

1.00
0.85
0.80

SEATING
PLANE

0.35
0.30
0.25

0.20 REF

COPLANARITY
0.08

FOR PROPER CONNECTION OF
THE EXPOSED PAD, REFER TO
THE PIN CONFIGURATION AND
FUNCTION DESCRIPTIONS
SECTION OF THIS DATA SHEET.

072808-A

COMPLIANT TO JEDEC STANDARDS MO-220-VGGC

Figure 43. 16-Lead Lead Frame Chip Scale Package [LFCSP_VQ]
4 mm × 4 mm Body, Very Thin Quad
(CP-16-4)
Dimensions shown in millimeters

8.75 (0.3445)
8.55 (0.3366)

14   8

4.00 (0.1575)
3.80 (0.1496)

1   7

6.20 (0.2441)
5.80 (0.2283)

1.27 (0.0500)
BSC

0.25 (0.0098)
0.10 (0.0039)

COPLANARITY
0.10

0.51 (0.0201)
0.31 (0.0122)

1.75 (0.0689)
1.35 (0.0531)

SEATING
PLANE

0.50 (0.0197)
0.25 (0.0098) × 45°

8°
0°

0.25 (0.0098)
0.17 (0.0067)

**1.27 (0.0500)**
0.40 (0.0157)

060606-A

COMPLIANT TO JEDEC STANDARDS MS-012-AB
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 44. 14-Lead Standard Small Outline Package [SOIC_N]
Narrow Body
(R-14)
Dimensions shown in millimeters and (inches)

ORDERING GUIDE

Model[1]	Temperature Range	Package Description	Package Option	Branding
ADA4004-1ARJZ-R2	−40°C to +125°C	5-Lead SOT-23	RJ-5	A1M
ADA4004-1ARJZ-R7	−40°C to +125°C	5-Lead SOT-23	RJ-5	A1M
ADA4004-1ARJZ-RL	−40°C to +125°C	5-lead SOT-23	RJ-5	A1M
ADA4004-1ARZ	−40°C to +125°C	8-Lead SOIC_N	R-8	
ADA4004-1ARZ-R7	−40°C to +125°C	8-Lead SOIC_N	R-8	
ADA4004-1ARZ-RL	−40°C to +125°C	8-Lead SOIC_N	R-8	
ADA4004-2ARMZ	−40°C to +125°C	8-Lead MSOP	RM-8	A1N
ADA4004-2ARMZ-RL	−40°C to +125°C	8-Lead MSOP	RM-8	A1N
ADA4004-2ARMZ-R7	−40°C to +125°C	8-Lead MSOP	RM-8	A1N
ADA4004-2ARZ	−40°C to +125°C	8-Lead SOIC_N	R-8	
ADA4004-2ARZ-RL	−40°C to +125°C	8-Lead SOIC_N	R-8	
ADA4004-2ARZ-R7	−40°C to +125°C	8-Lead SOIC_N	R-8	
ADA4004-4ACPZ-R2	−40°C to +125°C	16-Lead LFCSP_VQ	CP-16-4	
ADA4004-4ACPZ-R7	−40°C to +125°C	16-Lead LFCSP_VQ	CP-16-4	
ADA4004-4ACPZ-RL	−40°C to +125°C	16-Lead LFCSP_VQ	CP-16-4	
ADA4004-4ARZ	−40°C to +125°C	14-Lead SOIC_N	R-14	
ADA4004-4ARZ-R7	−40°C to +125°C	14-Lead SOIC_N	R-14	
ADA4004-4ARZ-RL	−40°C to +125°C	14-Lead SOIC_N	R-14	

[1] Z = RoHS Compliant Part.

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